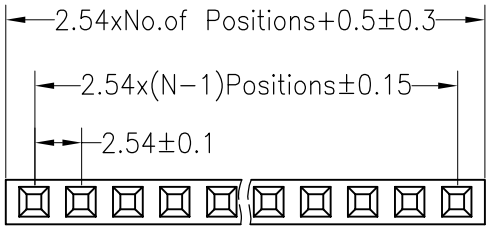
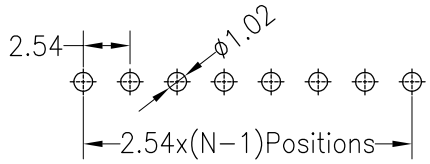
HSF RoHS

SPECIFICATIONS
Rated Current:3.0AMP
Contact Resistance:20mΩ Max
Withstand Voltage:1000V AC/DC
Insulation Resistance:1000MΩ Min
Operation Temperature:−40°c to +105°c

Contact Material:Brass
Contact Plating:Au or Sn Over Ni
Insulator Material:Polyester(UL94V−0)
Standard: PA6T
Max.Processing Temp: 230°C for 30−60 seconds
(260°C for 10 seconds)



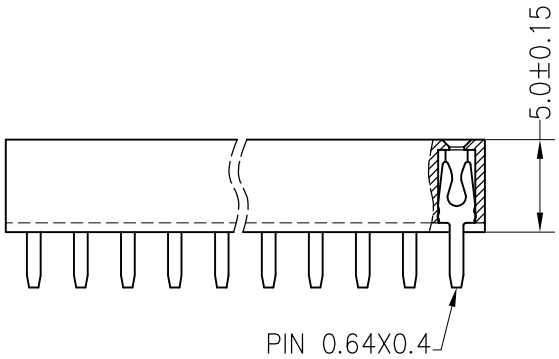
Recommended P.C.B Layout(Top Side)
(PCB BOARD TOLERANCE±0.05)

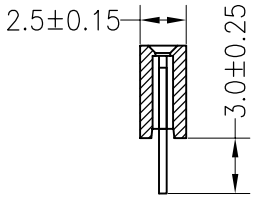


Ordering Information

2250 01 XX X N XX S Y X 01

- No.of Pins Per Row: 1*2~1*40
- Insulator Material Option: A=BK−PBT, B=BK−PA66, C=BK−PA6T, D=BK−PA46, E=BK−PA9T, F=BK−LCP
- Contact Plating: G0:Gold Flash, G1:3U" Gold, G2:5U" Gold, G3:10U" Gold, G4:15U" Gold, G5:30U" Gold, S0:Gold Flash/Tin, SN:Tin
- Packing: 0=PE Bag, T=Tube





REV	DATE	MODIFICATION DESCRIPTION	CHANGE
A0	2012.03.28	NEW DRAWING	

OPERATION		DRAW	Liu Miao		SCALE	FIT
X.X	±0.30				UNIT	mm
X.XX	±0.20	CHECK			SIZE	A4
X.XXX	±0.10				SHEET	1/1
Angle	±3°	APPROVE			PROJ.	
DIM	TOL					

WFD CONN 深圳市旺富达电子有限公司 SHEN ZHEN WFD ELECTRONICS CO., LTD

PART NO.	225001XXXNXXSYX01
TITLE:	2.54PF H5.0mm 1xNpin 180° DIP